STARPOWER

SEMICONDUCTOR

MOSFET

MD350HFR120B3S

1200V/350A 2 in one-package

General Description

STARPOWER MOSFET Power Module provides very low $R_{DS(on)}$ as well as optimized intrinsic diode. It's designed for the applications such SMPS and DC drives.

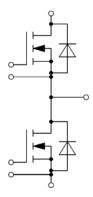
Features

- SiC power MOSFET
- Low $R_{DS(on)}$
- Optimized intrinsic reverse diode
- Chip sintering technology
- Low inductance case avoid oscillations
- Isolated copper baseplate using DBC technology

Typical Applications

- Main and auxiliary AC drives of electric vehicles
- DC servo and robot drives
- Battery vehicles
- UPS equipment
- Plasma cutting

Equivalent Circuit Schematic



Absolute Maximum Ratings

MOSFET

Symbol	Description	Value	Unit	
$V_{ m DSS}$	Drain-Source Voltage	1200	V	
V_{GSS}	Gate-Source Voltage	±20	V	
	Drain Current @ T _C =25°C	473	٨	
\mathbf{I}_{D}	@ T _C =90°C	350	A	
I_{DM}	Pulsed Drain Current	1370	A	

Inverse Diode

Symbol	Description	Value	Unit
I_S	Source Current	350	A
I_{SM}	Pulsed Source Current	1370	A

Module

Symbol	Description	Value	Unit
T_{jmax}	Maximum Junction Temperature	175	°C
T_{jop}	Operating Junction Temperature	-40 to +150	°C
T_{STG}	Storage Temperature Range	-40 to +125	°C
$V_{\rm ISO}$	Isolation Voltage RMS,f=50Hz,t=1min	4000	V

MOSFET Characteristics

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$R_{DS(on)}$	Static Drain-Source	$I_D=200A, V_{GS}=18V, T_j=25^{\circ}C$		4.0	5.2	· mΩ
	On-Resistance	I _D =200A,V _{GS} =18V, T _i =125°C		6.0		
$V_{\text{GS(th)}}$	Gate-Source Threshold Voltage	$I_D=100$ mA, $V_{DS}=V_{GS}$, $T_i=25$ °C	2.7		5.6	V
g_{fs}	Forward Transconductance	V _{DS} =10V,I _D =200A		83		S
I_{DSS}	Drain-Source Leakage Current	$V_{DS}=V_{DSS}, V_{GS}=0V,$ $T_j=25^{\circ}C$			100	μΑ
I_{GSS}	Gate-Source Leakage Current	$V_{GS}=V_{GSS}, V_{DS}=0V,$ $T_j=25^{\circ}C$			1	μΑ
C_{iss}	Input Capacitance			13.4		nF
C_{oss}	Output Capacitance	$V_{GS} = 0V, V_{DS} = 800V,$		0.75		nF
C_{rss}	Reverse Transfer Capacitance	f=1MHz		0.28		nF
Q_{g}	Total Gate Charge			1070		nC
Q_{gs}	Gate-Source Charge	$I_D = 200A, V_{DS} = 600V,$		220		nC
$Q_{gd} \\$	Gate-Drain ("Miller") Charge	$V_{GS}=18V$		410		nC
t _{d(on)}	Turn-On Delay Time	V -400VI -190A		21		ns
$t_{\rm r}$	Rise Time	V_{DS} =400V, I_{D} =180A, R_{G} =0 Ω , V_{GS} =18V, T_{j} =25°C		39		ns
$t_{ m d(off)}$	Turn-Off Delay Time			49		ns
t_{f}	Fall Time			24		ns
E_{on}	Turn-On Switching Loss	V _{DS} =600V,I _D =200A,		2.83		mJ
$E_{ m off}$	Turn-Off Switching Loss	$R_G=0\Omega, V_{GS}=18V,$ $T_j=25^{\circ}C$		1.18		mJ

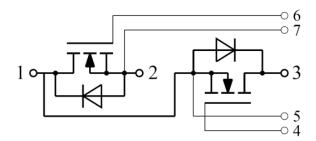
Inverse Diode Characteristics

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V_{SD}	Diode Forward Voltage	$I_{S}=200A, V_{GS}=0V, T_{j}=25^{\circ}C$		3.2		V
t_{rr}	Diode Reverse Recovery Time	$\begin{array}{c} V_{R}{=}600V, I_{S}{=}200A, \\ -di/dt{=}22000A/\mu s, \\ T_{j}{=}25^{\circ}C \end{array}$		25		ns
Q_{r}	Diode Reverse Recovery Charge			1.15		μС
I_{RM}	Peak Reverse Recovery Current			90		A

Module Characteristics $T_C=25^{\circ}C$ unless otherwise noted

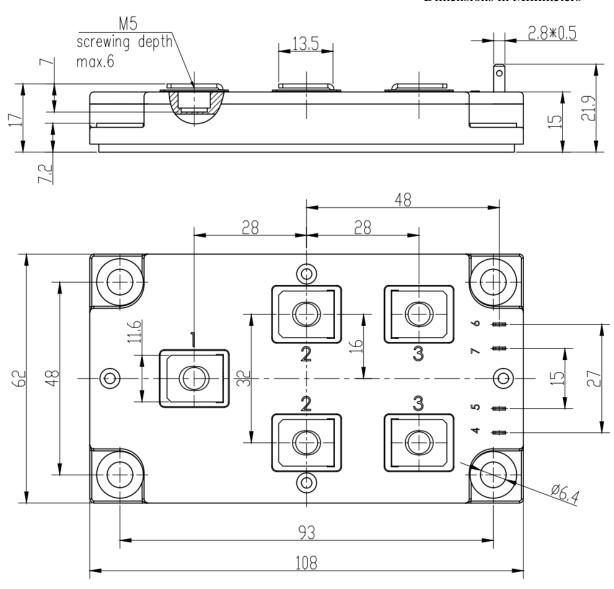
Symbol	Parameter		Typ.	Max.	Unit
R_{thJC}	Junction-to-Case(Mosfet)			0.081	K/W
R _{thCH}	Case-to-Heatsink (Mosfet)		0.020		K/W
	Case-to-Heatsink (per Module)		0.010		K/W
M	Terminal Connection Torque, Screw M5	2.5		5.0	N.m
	Mounting Torque, Screw M6	3.0		5.0	.0
G	Weight of Module		300		g

Circuit Schematic



Package Dimensions

Dimensions in Millimeters



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